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(54) Title: IMPLEMENTATION OF TWO-PHASE COLD PLATE LOOPS WITH DESIGN FEATURES TO OPTIMIZE THERMOFLUIDIC PERFORMANCE IN SPACE CONSTRAINED COMPUTER ARCHITECTURES

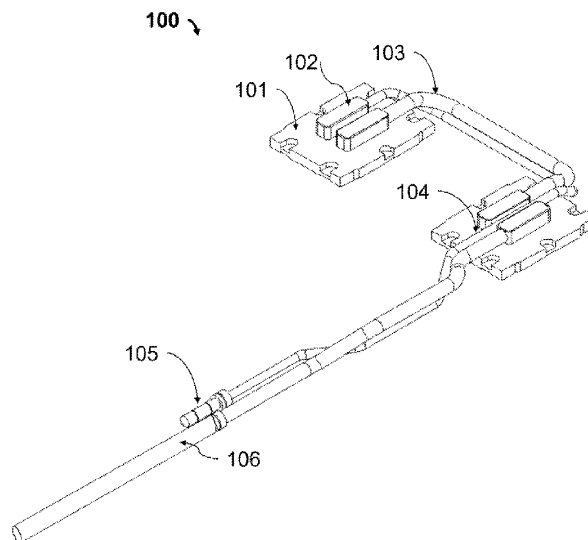


Figure 1 Example of a dual socket cold plate loop implementation comprised of formed tubing in a serial flow configuration.

(57) Abstract: Arrangements, sub-systems, devices and methods for providing cooling to hardware components, and more specifically to server cold plate loop (CPL) sub-systems, devices and methods for thermal management of hardware in computer server racks and related equipment in computer data centers.

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